	Туре	Hits	Search Text	DBs
1	BRS	1579110	(circuit near3 (board or structure)) or substrate	USPAT; EPO; JPO; DERWENT; IBM_TDB
2	BRS	257	(low adj temperature) and (co-fire\$2 adj ceramic)	USPAT; EPO; JPO; DERWENT; IBM_TDB
3	BRS	262	LTCC	USPAT; EPO; JPO; DERWENT; IBM_TDB
4	BRS	392	((low adj temperature) and (co-fire\$2 adj ceramic)) or LTCC	USPAT; EPO; JPO; DERWENT; IBM_TDB
5	BRS	316	((circuit near3 (board or structure)) or substrate) and (((low adj temperature) and (co-fire\$2 adj ceramic)) or LTCC)	USPAT; EPO; JPO; DERWENT; IBM_TDB
6	BRS	48	(((circuit near3 (board or structure)) or substrate) and (((low adj temperature) and (co-fire\$2 adj ceramic)) or LTCC)) and barrier	USPAT; EPO; JPO; DERWENT; IBM_TDB
7	BRS	256	(((circuit near3 (board or structure)) or substrate) and (((low adj temperature) and (co-fire\$2 adj ceramic)) or LTCC)) and (via\$1 or hole\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
8	BRS	60	(((circuit near3 (board or structure)) or substrate) and (((low adj temperature) and (co-fire\$2 adj ceramic)) or LTCC)) not ((((circuit near3 (board or structure)) or substrate) and (((low adj temperature) and (co-fire\$2 adj ceramic)) or LTCC)) and (via\$1 or hole\$1))	USPAT; EPO; JPO; DERWENT; IBM_TDB
9	IS&R	884	(174/255).CCLS.	USPAT
10	BRS	319	((174/255).CCLS.) and (mask or resist)	USPAT
11	BRS	135	(((174/255).CCLS.) and (mask or resist)) and ceramic	USPAT
12	BRS	65836	174/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB
13	BRS	91808	361/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB
14	BRS	144515	257/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB
15	BRS	162467	29/\$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB
16	BRS	13464	h05k001/03	USPAT; EPO; JPO; DERWENT; IBM_TDB
17	BRS	6538	h05k001/09	USPAT; EPO; JPO; DERWENT; IBM_TDB
18	BRS	455359	OF Z9/M CCIS OF HUDKUUT/US OF	USPAT; EPO; JPO; DERWENT; IBM_TDB

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	Туре	Hits	Search Text	DBs
19	BRS	1242	(174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (ceramic adj layer)	USPAT; EPO; JPO; DERWENT; IBM_TDB
20	BRS	132082	(174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (hole\$1 or via\$1 or aperture\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
21	BRS	22879	(174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB
22	BRS	626	((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (ceramic adj layer)) and ((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (hole\$1 or via\$1 or aperture\$1))	USPAT; EPO; JPO; DERWENT; IBM_TDB
23	BRS	72	((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (barrier)) and (((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (ceramic adj layer)) and ((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and (hole\$1 or via\$1 or aperture\$1)))	USPAT; EPO; JPO; DERWENT; IBM_TDB
24	BRS	28616	(174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic	USPAT; EPO; JPO; DERWENT; IBM_TDB
25	BRS	14476	((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (hole\$1 or via\$1 or aperture\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
26	BRS	14476	((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (hole\$1 or via\$1 or aperture\$1))	USPAT; EPO; JPO; DERWENT; IBM_TDB
27	BRS	3839	(((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (hole\$1 or via\$1 or aperture\$1))) and pad	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Туре	Hits	Search Text	DBs
28	BRS	1382	((((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (hole\$1 or via\$1 or aperture\$1))) and pad) and (mask or resist)	USPAT; EPO; JPO; DERWENT; IBM_TDB
29	BRS	841	(((((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (hole\$1 or via\$1 or aperture\$1))) and pad) and (mask or resist)) and glass	USPAT; EPO; JPO; DERWENT; IBM_TDB
30	BRS	185	(((((((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (((174/\$.ccls. or 361/\$.ccls. or 257/\$.ccls. or 29/\$.ccls. or h05k001/03 or h05k001/09) and ceramic) and (hole\$1 or via\$1 or aperture\$1))) and pad) and (mask or resist)) and glass) and barrier	USPAT; EPO; JPO; DERWENT; IBM_TDB

DBs
DBs

	Time Stamp	Comments	Error Definition	Errors
1	Time Stamp 2002/11/16 13:53		Definition	Errors 0

Туре	Hits	Search Text	DBs
2 BRS 8	50	("6061228" "5498905" "5412539" "5600541" "6419980" "5455385" "5611876" "5376574" "5571740" "5386339" "5178051" "5217216" "5789815" "5315239" "5318820" "5402003" "5429859" "5502002" "6099677" "6387507" "6387507" "6395374" "5406122" "5438167" "5937321" "6205032" "5855803" "6408511" "5249355" "5347091" "5661882" "5744232"	USPAT

	Time Stamp	Comments	Error Definition	Errors
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2	2002/11/16 14:53			0

	Type	Hits	Search Text	DBs
			("5847286"	
			` 5859614"	
			"5937125"	
			"5977915"	
			"5990028"	
			"6064281"	
		‡	"6091312"	
			"6147019"	
			"6217821"	
			"6217821"	
	:		"6252761"	
			"6278180"	
			"6284080"	
			"6373348"	
			"5585675"	
			<u>"5</u> 176771"	
3	BRS	48	"5708570"	USPAT
			"6228788"	
			"5461196"	
]		"5601673"	
			"5683535"	
			"5740594"	
			"5747873"	
			"5780375"	
			"5812035"	
			"5876539"	
			"5919325"	
			"6008535"	
			"6181562" "6180007"	
			"6190997"	
			"6211824" "6244824"	
			"6211824"	

Туре	Hits	Search Text	DBs
4 BRS	48	("5904499" "5920200" "6002168" "6165820" "6208025" "6234842" "6268739" "6288559" "6380616" "5701233" "5714246" "6437981" "5982250" "5757252" "5930665" "5611696" "5968670" "4420203" "4629267" "4843315" "5027191" "5221209" "5237269" "5237269" "5308250" "5427535" "5453690" "5477159" "5495179" "5576630" "5686842" "58444418"	USPAT

Туре	Hits	Search Text	DBs
5 BRS	50	("5633783" "5653841" "5776275" "5808875" "5866952" "6050832" "6150719" "6168972" "6194905" "6281844" "4992849" "4992850" RE36325 "5313091" "6340894" "5747095" "5757079" "4430365" "5483105" "4444559" "4521449" "4562513" "5280413" "5294754" "5354955" "5383269" "57722579" "5779320" "5788808" "6002172" "6002267" "6165885"	USPAT

	Туре	Hits	Search Text	DBs
6	BRS	50	"5740010" "5742025" "5763854" "5818699" "5831336" "5852257" "5872051" "5949654" "5953623" "5950907" "6025649" "6064116" "6072236" "6124634" "6159817" "6196443" "6207548" "6427324" "4439813" "5288944" "5367195" "5420073" "5565385" "4504322" "4509096" "4511425" "4549200" "4873615" "4903120" "4910643"	USPAT
7	BRS	18954	circuit adj structure	USPAT; EPO; JPO; DERWENT; IBM_TDB
8	BRS	218633	circuit adj board	USPAT; EPO; JPO; DERWENT; IBM_TDB
9	BRS	48107	wiring adj board	USPAT; EPO; JPO; DERWENT; IBM_TDB
10	BRS	277495	(circuit adj structure) or (circuit adj board) or (wiring adj board)	USPAT; EPO; JPO; DERWENT; IBM_TDB
11	BRS	22094	((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic	USPAT; EPO; JPO; DERWENT; IBM_TDB
12	BRS	14802	(((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Туре	Hits	Search Text	DBs
13	BRS	807	((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (conductive adj paste)	USPAT; EPO; JPO; DERWENT; IBM_TDB
14	BRS	o	((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (barrier adj cap)	USPAT; EPO; JPO; DERWENT; IBM_TDB
15	BRS	1435	((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB
16	BRS	876	(((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (barrier)) and (pad\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
17	BRS	5544	((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (capacitor\$1 or resistor\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
18	BRS	663	(((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (barrier)) and ((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and ceramic) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (capacitor\$1 or resistor\$1))	USPAT; EPO; JPO; DERWENT; IBM_TDB
19	BRS	3197	((circuit adj structure) or (circuit adj board) or (wiring adj board)) and (ceramic near3 layer\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
20	BRS	2140	(((circuit adj structure) or (circuit adj board) or (wiring adj board)) and (ceramic near3 layer\$1)) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
21	BRS	899	((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and (ceramic near3 layer\$1)) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (capacitor\$1 or resistor\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB

	Туре	Hits	Search Text	DBs
22	BRS	247	((((circuit adj structure) or (circuit adj board) or (wiring adj board)) and (ceramic near3 layer\$1)) and (via\$1 or hole\$1 or aperture\$1 or opening\$1)) and (barrier)	USPAT; EPO; JPO; DERWENT; IBM_TDB
23	BRS	0	(wiring adj board).ti,ab. and (ceramic adj layer\$1) and (barrier) and (via\$1 or hole\$1)	USPAT
24	BRS	8	(circuit adj board).ti,ab. and (ceramic adj layer\$1) and (barrier) and (via\$1 or hole\$1)	USPAT
25	BRS	3	(circuit adj structure).ti,ab. and (ceramic adj layer\$1) and (barrier) and (via\$1 or hole\$1)	USPAT
26	BRS	1	(wiring adj structure).ti,ab. and (ceramic adj layer\$1) and (barrier) and (via\$1 or hole\$1)	USPAT
27	BRS	3	(circuit adj structure).ti,ab. and (ceramic adj layer\$1) and (barrier) and (via\$1 or hole\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
28	BRS	1	(wiring adj structure).ti,ab. and (ceramic adj layer\$1) and (barrier) and (via\$1 or hole\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB
29	BRS	129	barrier adj cap	USPAT; EPO; JPO; DERWENT; IBM_TDB
30	BRS	38820	"68" and ceramic	USPAT; EPO; JPO; DERWENT; IBM_TDB
31	BRS	7	((barrier adj cap) and (via\$1 or hole\$1)) and ceramic	USPAT; EPO; JPO; DERWENT; IBM_TDB
32	BRS	68	(barrier adj cap) and (via\$1 or hole\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB